The ornamental design for a semiconductor chip package, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view from the left side and above the semiconductor chip package;

FIG. 2 is a perspective view from the left side and below the semiconductor chip package;

FIG. 3 is an elevational view from the left side of the semiconductor chip package;

FIG. 4 is an elevational view from the right side of the semiconductor chip package;

FIG. 5 is an elevational view from the back side of the semiconductor chip package;

FIG. 6 is an elevational view from the front side of the semiconductor chip package;

FIG. 7 is a top view of the semiconductor chip package; and,

FIG. 8 is a bottom view of the semiconductor chip package.

1 Claim, 8 Drawing Sheets